

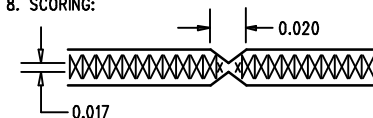
SIZE	QTY	SYM	PLTD	TOL
10	330	+	YES	+/-0.0
94	3	X	YES	+/-0.0

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


4 LAYERS	.0028"	Microstrip
	⑦ .018"	Core Material
	.0014"	Microstrip
	.062"	Prepreg
	.0014"	Microstrip
	⑦ .018"	Core Material
	.0028"	Microstrip

NOTES : Unless Otherwise Specified

1. MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4. 1 OZ. COPPER ON INTERNAL LAYER. 2 OZ. COPPER ON OUTER LAYER. THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS
2. DRILLING: DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, .001 INCH THICK MIN. ALL HOLE SIZES ARE SPECIFIED AFTER PLATING. HOLE LOCATION TOLERANCES ARE +/- .003 INCH IN RELATION TO CENTER
3. SOLDER MASK : SMOBC BOTH SIDES USING LPI.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK
5. ALL DIMENSIONS ARE IN INCHES
6. CONTROLLED 50 OHM IMPEDANCE (AT 6 GHz FREQ.) FOR LAYER 1-2 AND LAYER 4-3.
- ⑦ SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.
8. SCORING:



FAB DRAWING

APPROVALS			 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN			TITLE: I/Q Modulator w/Current BB Interface	
CHECK				
DESIGN	Rudy B			
ENGR	Doug S.			
			SIZE A	REV. 1
SCALE = NONE			DEMO DC729A	SHT 1 of 1